

74HC125; 74HCT125

Quad buffer/line driver; 3-state

Rev. 5 — 19 January 2015

Product data sheet

1. General description

The 74HC125; 74HCT125 is a quad buffer/line driver with 3-state outputs controlled by the output enable inputs ($n\text{OE}$). A HIGH on $n\text{OE}$ causes the outputs to assume a high impedance OFF-state. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

2. Features and benefits

- Complies with JEDEC standard no. 7A
- Input levels:
 - ◆ The 74HC125: CMOS levels
 - ◆ The 74HCT125: TTL levels
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Ordering information

Table 1. Ordering information

| Type number | Package | | | |
|-------------|---|---------|--|----------|
| | Temperature range | Name | Description | Version |
| 74HC125N | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | DIP14 | plastic dual in-line package; 14 leads (300 mil) | SOT27-1 |
| 74HCT125N | | | | |
| 74HC125D | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | SO14 | plastic small outline package; 14 leads; body width 3.9 mm | SOT108-1 |
| 74HCT125D | | | | |
| 74HC125DB | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | SSOP14 | plastic shrink small outline package; 14 leads; body width 5.3 mm | SOT337-1 |
| 74HCT125DB | | | | |
| 74HC125PW | $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$ | TSSOP14 | plastic thin shrink small outline package; 14 leads; body width 4.4 mm | SOT402-1 |
| 74HCT125PW | | | | |

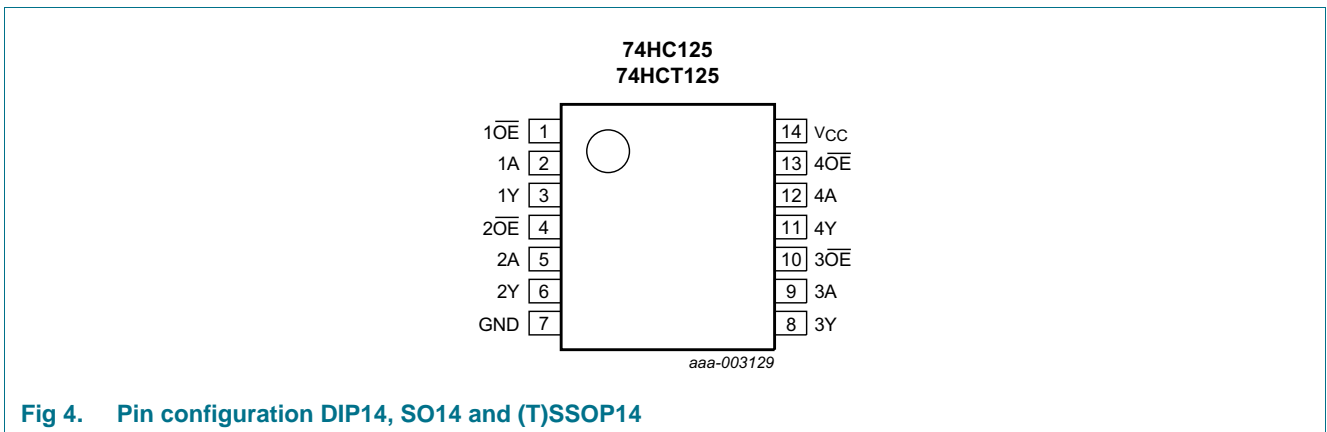


4. Functional diagram



5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

| Symbol | Pin | Description |
|---|--------------|----------------------------------|
| $1\overline{OE}$, $2\overline{OE}$, $3\overline{OE}$, $4\overline{OE}$ | 1, 4, 10, 13 | output enable input (active LOW) |
| 1A, 2A, 3A, 4A | 2, 5, 9, 12 | data input |
| 1Y, 2Y, 3Y, 4Y | 3, 6, 8, 11 | data output |
| GND | 7 | ground (0 V) |
| V _{CC} | 14 | supply voltage |

6. Functional description

Table 3. Function table^[1]

| Control | Input | Output |
|------------------|-------|--------|
| \overline{nOE} | nA | nY |
| L | L | L |
| | H | H |
| H | X | Z |

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|------------------|-----------------------------|---|------|------|------|
| V _{CC} | supply voltage | | -0.5 | +7 | V |
| I _{IK} | input clamping current | V _I < -0.5 V or V _I > V _{CC} + 0.5 V | [1] | ±20 | mA |
| I _{OK} | output clamping current | V _O < -0.5 V or V _O > V _{CC} + 0.5 V | [1] | ±20 | mA |
| I _O | output current | V _O = -0.5 V to (V _{CC} + 0.5 V) | - | ±35 | mA |
| I _{CC} | supply current | | - | +70 | mA |
| I _{GND} | ground current | | - | -70 | mA |
| T _{stg} | storage temperature | | -65 | +150 | °C |
| P _{tot} | total power dissipation | | [2] | | |
| | DIP14 package | | - | 750 | mW |
| | SO14 and (T)SSOP14 packages | | - | 500 | mW |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For DIP14 package: P_{tot} derates linearly with 12 mW/K above 70 °C.

For SO14 package: P_{tot} derates linearly with 8 mW/K above 70 °C.

For (T)SSOP14 packages: P_{tot} derates linearly with 5.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

| Symbol | Parameter | Conditions | 74HC125 | | | 74HCT125 | | | Unit |
|------------------|-------------------------------------|-------------------------|---------|------|-----------------|----------|------|-----------------|------|
| | | | Min | Typ | Max | Min | Typ | Max | |
| V _{CC} | supply voltage | | 2.0 | 5.0 | 6.0 | 4.5 | 5.0 | 5.5 | V |
| V _I | input voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| V _O | output voltage | | 0 | - | V _{CC} | 0 | - | V _{CC} | V |
| T _{amb} | ambient temperature | | -40 | +25 | +125 | -40 | +25 | +125 | °C |
| Δt/ΔV | input transition rise and fall rate | V _{CC} = 2.0 V | - | - | 625 | - | - | - | ns/V |
| | | V _{CC} = 4.5 V | - | 1.67 | 139 | - | 1.67 | 139 | ns/V |
| | | V _{CC} = 6.0 V | - | - | 83 | - | - | - | ns/V |

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|-----------------|---------------------------|--|-------|------|------|------------------|------|-------------------|-------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74HC125 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 2.0 V | 1.5 | 1.2 | - | 1.5 | - | 1.5 | - | V |
| | | V _{CC} = 4.5 V | 3.15 | 2.4 | - | 3.15 | - | 3.15 | - | V |
| | | V _{CC} = 6.0 V | 4.2 | 3.2 | - | 4.2 | - | 4.2 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 2.0 V | - | 0.8 | 0.5 | - | 0.5 | - | 0.5 | V |
| | | V _{CC} = 4.5 V | - | 2.1 | 1.35 | - | 1.35 | - | 1.35 | V |
| | | V _{CC} = 6.0 V | - | 2.8 | 1.8 | - | 1.8 | - | 1.8 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = -20 μA; V _{CC} = 2.0 V | 1.9 | 2.0 | - | 1.9 | - | 1.9 | - | V |
| | | I _O = -20 μA; V _{CC} = 4.5 V | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -20 μA; V _{CC} = 6.0 V | 5.9 | 6.0 | - | 5.9 | - | 5.9 | - | V |
| | | I _O = -6.0 mA; V _{CC} = 4.5 V | 3.98 | 4.32 | - | 3.84 | - | 3.7 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = 20 μA; V _{CC} = 2.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 4.5 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 20 μA; V _{CC} = 6.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 6.0 mA; V _{CC} = 4.5 V | - | 0.15 | 0.26 | - | 0.33 | - | 0.4 | V |
| I _{OZ} | OFF-state output current | I _O = 7.8 mA; V _{CC} = 6.0 V | - | 0.16 | 0.26 | - | 0.33 | - | 0.4 | V |
| | | V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND; V _{CC} = 6.0 V | - | - | ±0.1 | - | ±1.0 | - | ±1.0 | μA |
| I _{OZ} | OFF-state output current | V _I = V _{IH} or V _{IL} ; V _O = V _{CC} or GND; V _{CC} = 6.0 V | - | - | ±0.5 | - | ±5.0 | - | ±10.0 | μA |

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|------------------|---------------------------|---|-------|------|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V | - | - | 8.0 | - | 80 | - | 160 | μA |
| C _I | input capacitance | | - | 3.5 | - | | | | | pF |
| 74HCT125 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 4.5 V to 5.5 V | 2.0 | 1.6 | - | 2.0 | - | 2.0 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 4.5 V to 5.5 V | - | 1.2 | 0.8 | - | 0.8 | - | 0.8 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = -20 μA | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = -6 mA | 3.98 | 4.32 | - | 3.84 | - | 3.7 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = 20 μA | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 6.0 mA | - | 0.16 | 0.26 | - | 0.33 | - | 0.4 | V |
| I _I | input leakage current | V _I = V _{CC} or GND; V _{CC} = 5.5 V | - | - | ±0.1 | - | ±1.0 | - | ±1.0 | μA |
| I _{OZ} | OFF-state output current | V _I = V _{IH} or V _{IL} ; V _{CC} = 5.5 V; V _O = V _{CC} or GND | - | - | ±0.5 | - | ±5.0 | - | ±10 | μA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 8.0 | - | 80 | - | 160 | μA |
| ΔI _{CC} | additional supply current | per input pin; V _I = V _{CC} - 2.1 V; I _O = 0 A; other inputs at V _{CC} or GND; V _{CC} = 4.5 V to 5.5 V | - | 100 | 360 | - | 450 | - | 490 | μA |
| C _I | input capacitance | | - | 3.5 | - | | | | | pF |

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); $C_L = 50$ pF unless otherwise specified; for test circuit see [Figure 7](#).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|----------------|-------------------------------|--|-------|-----|-----|------------------|-----|-------------------|-----|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74HC125 | | | | | | | | | | |
| t_{pd} | propagation delay | nA to nY; see Figure 5 ^[1] | | | | | | | | |
| | | $V_{CC} = 2.0$ V | - | 30 | 100 | - | 125 | - | 150 | ns |
| | | $V_{CC} = 4.5$ V | - | 11 | 20 | - | 25 | - | 30 | ns |
| | | $V_{CC} = 5$ V; $C_L = 15$ pF | - | 9 | - | - | - | - | - | ns |
| | | $V_{CC} = 6.0$ V | - | 9 | 17 | - | 21 | - | 26 | ns |
| t_{en} | enable time | nOE to nY; see Figure 6 ^[2] | | | | | | | | |
| | | $V_{CC} = 2.0$ V | - | 41 | 125 | - | 155 | - | 190 | ns |
| | | $V_{CC} = 4.5$ V | - | 15 | 25 | - | 31 | - | 38 | ns |
| | | $V_{CC} = 6.0$ V | - | 12 | 21 | - | 26 | - | 32 | ns |
| t_{dis} | disable time | nOE to nY; see Figure 6 ^[3] | | | | | | | | |
| | | $V_{CC} = 2.0$ V | - | 41 | 125 | - | 155 | - | 190 | ns |
| | | $V_{CC} = 4.5$ V | - | 15 | 25 | - | 31 | - | 38 | ns |
| | | $V_{CC} = 6.0$ V | - | 12 | 21 | - | 26 | - | 32 | ns |
| t_t | transition time | nY; see Figure 5 ^[4] | | | | | | | | |
| | | $V_{CC} = 2.0$ V | - | 14 | 60 | - | 75 | - | 90 | ns |
| | | $V_{CC} = 4.5$ V | - | 5 | 12 | - | 15 | - | 18 | ns |
| | | $V_{CC} = 6.0$ V | - | 4 | 10 | - | 13 | - | 15 | ns |
| C_{PD} | power dissipation capacitance | $C_L = 50$ pF; $f = 1$ MHz; $V_I = \text{GND to } V_{CC}$ ^[5] | - | 22 | - | - | - | - | - | pF |

Table 7. Dynamic characteristics ...continued

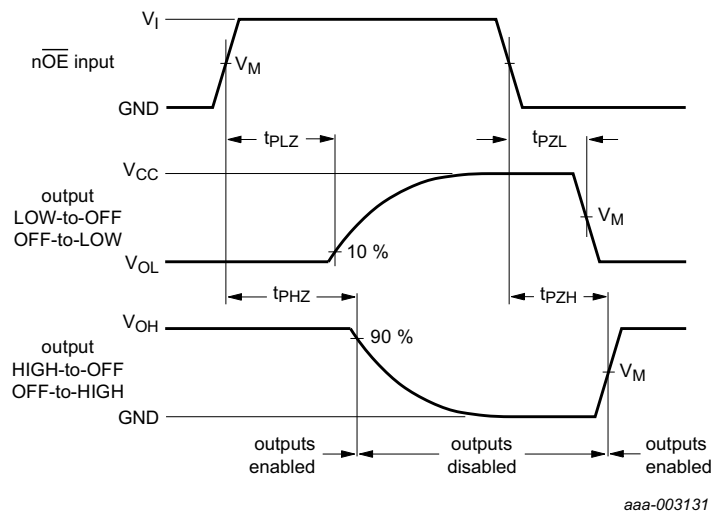
Voltages are referenced to GND (ground = 0 V); $C_L = 50 \text{ pF}$ unless otherwise specified; for test circuit see [Figure 7](#).

| Symbol | Parameter | Conditions | 25 °C | | | -40 °C to +85 °C | | -40 °C to +125 °C | | Unit |
|-----------------|-------------------------------|---|-------|-----|-----|------------------|-----|-------------------|-----|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| 74HCT125 | | | | | | | | | | |
| t_{pd} | propagation delay | nA to nY; see Figure 5 [1] | | | | | | | | |
| | | $V_{CC} = 4.5 \text{ V}$ | - | 15 | 25 | - | 31 | - | 38 | ns |
| | | $V_{CC} = 5 \text{ V}; C_L = 15 \text{ pF}$ | - | 12 | - | - | - | - | - | ns |
| t_{en} | enable time | \overline{nOE} to nY; see Figure 6 [2] | | | | | | | | |
| | | $V_{CC} = 4.5 \text{ V}$ | - | 15 | 28 | - | 35 | - | 42 | ns |
| t_{dis} | disable time | \overline{nOE} to nY; see Figure 6 [3] | | | | | | | | |
| | | $V_{CC} = 4.5 \text{ V}$ | - | 15 | 25 | - | 31 | - | 38 | ns |
| t_t | transition time | nY; see Figure 5 [4] | - | 5 | 12 | - | 15 | - | 18 | ns |
| C_{PD} | power dissipation capacitance | $C_L = 50 \text{ pF}; f = 1 \text{ MHz}; V_1 = \text{GND to } V_{CC} - 1.5 \text{ V}$ [5] | - | 24 | - | - | - | - | - | pF |

- [1] t_{pd} is the same as t_{PLH} and t_{PHL} .
- [2] t_{en} is the same as t_{PZH} and t_{PZL} .
- [3] t_{dis} is the same as t_{PLZ} and t_{PHZ} .
- [4] t_t is the same as t_{THL} and t_{TLH} .
- [5] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 C_L = output load capacitance in pF;
 V_{CC} = supply voltage in V;
 N = number of inputs switching;
 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

11. Waveforms





Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Enable and disable times

Table 8. Measurement points

| Type | Input | Output |
|----------|-------------|-------------|
| | V_M | V_M |
| 74HC125 | $0.5V_{CC}$ | $0.5V_{CC}$ |
| 74HCT125 | 1.3 V | 1.3 V |



Test data is given in [Table 9](#).

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistance.

S1 = Test selection switch.

Fig 7. Load circuit for switching times

Table 9. Test data

| Type | Input | | Load | | S1 position | | |
|----------|----------|------------|--------------|--------------|--------------------|--------------------|--------------------|
| | V_I | t_r, t_f | C_L | R_L | t_{PHL}, t_{PLH} | t_{PZH}, t_{PHZ} | t_{PZL}, t_{PLZ} |
| 74HC125 | V_{CC} | 6 ns | 15 pF, 50 pF | 1 k Ω | open | GND | V_{CC} |
| 74HCT125 | 3 V | 6 ns | 15 pF, 50 pF | 1 k Ω | open | GND | V_{CC} |

12. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1

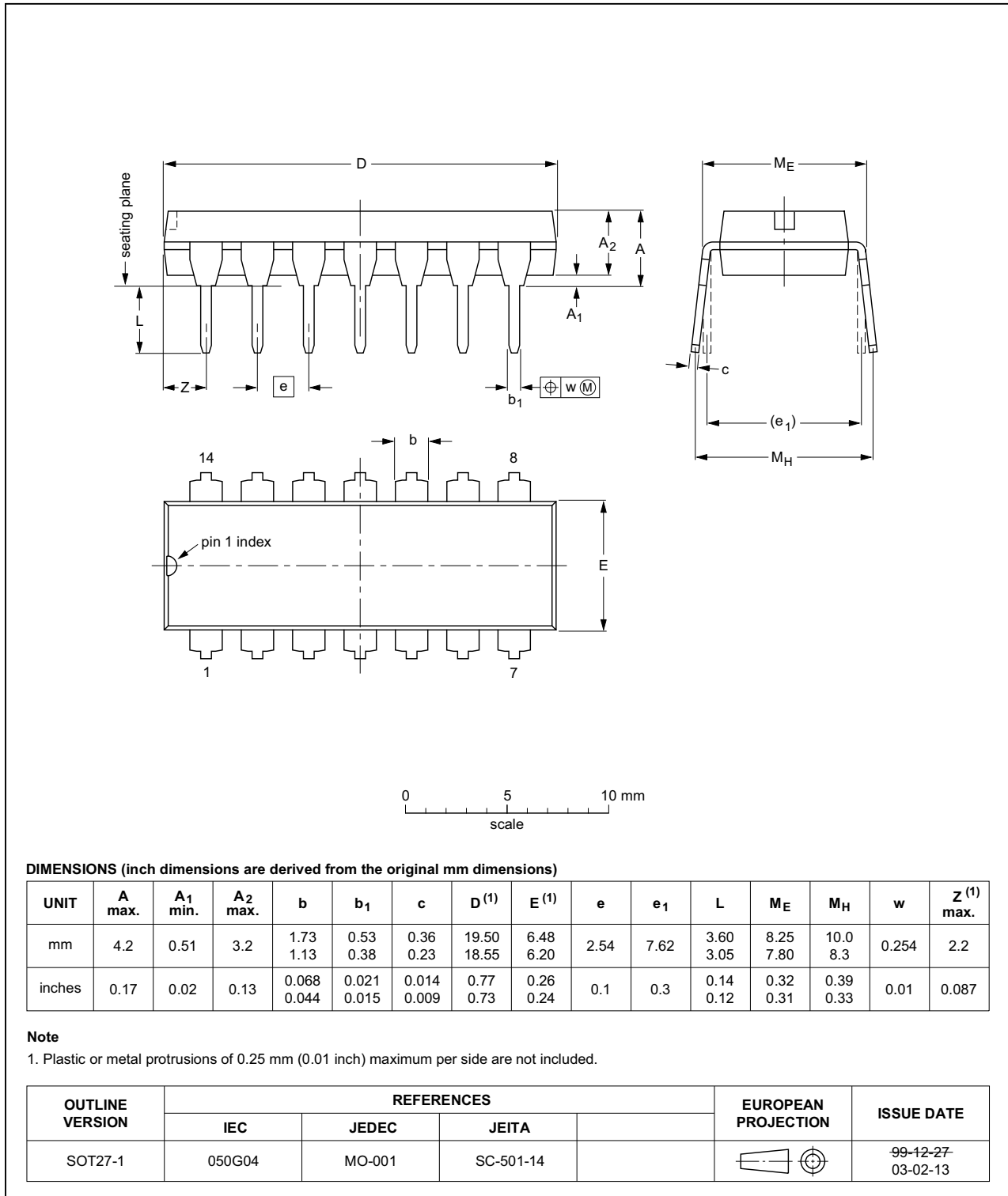


Fig 8. Package outline SOT27-1 (DIP14)

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

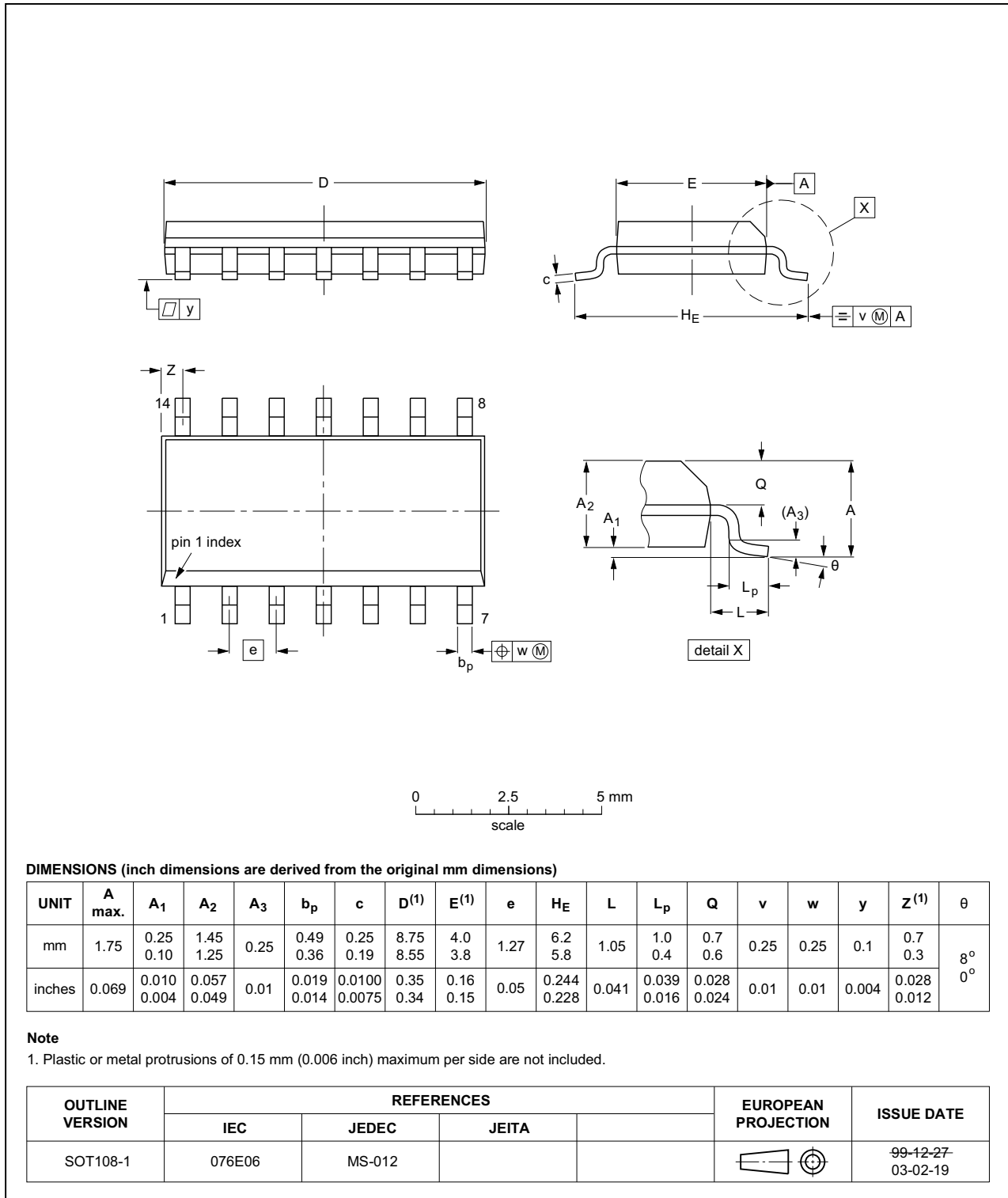


Fig 9. Package outline SOT108-1 (SO14)

SSOP14: plastic shrink small outline package; 14 leads; body width 5.3 mm

SOT337-1

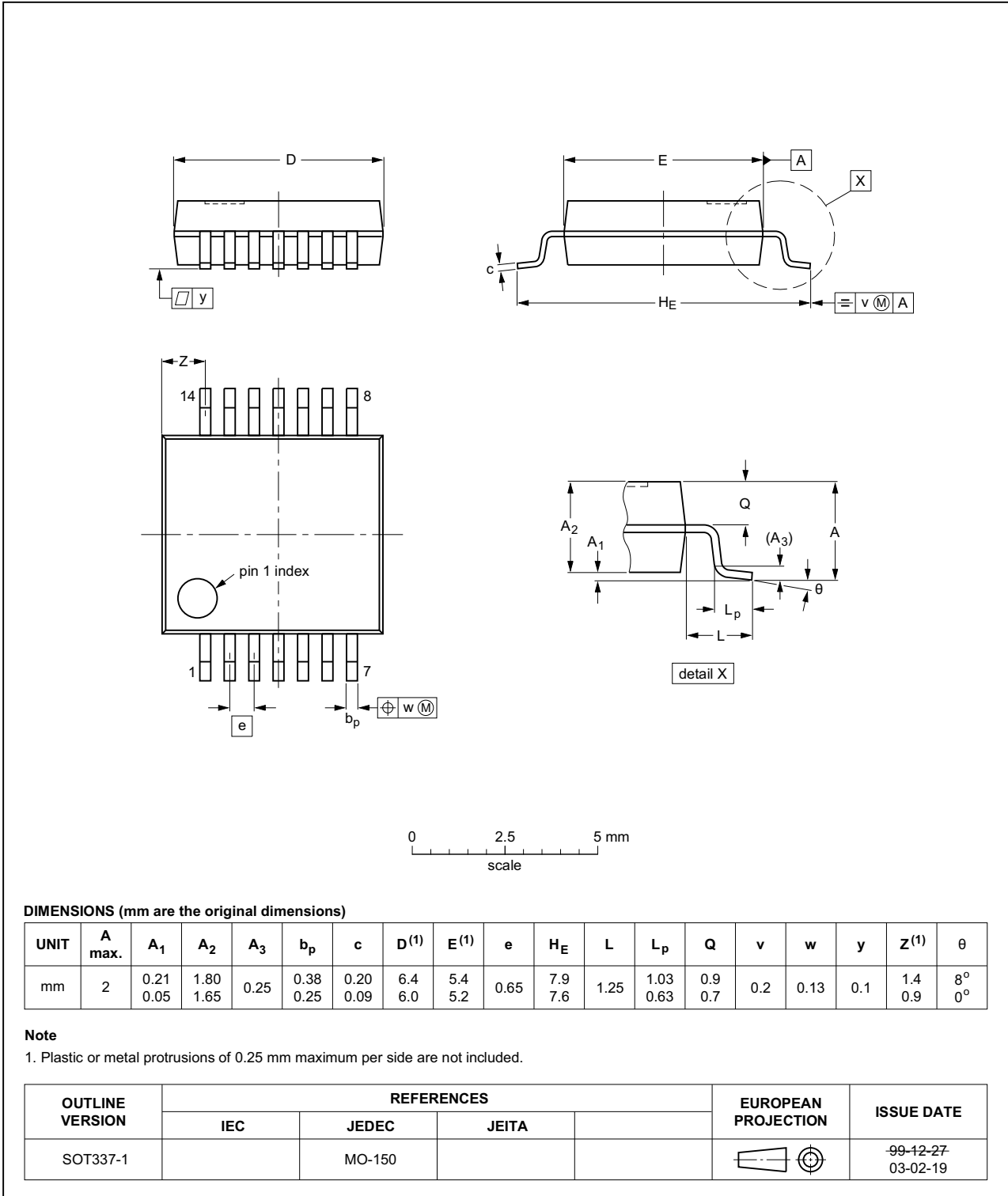


Fig 10. Package outline SOT337-1 (SSOP14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

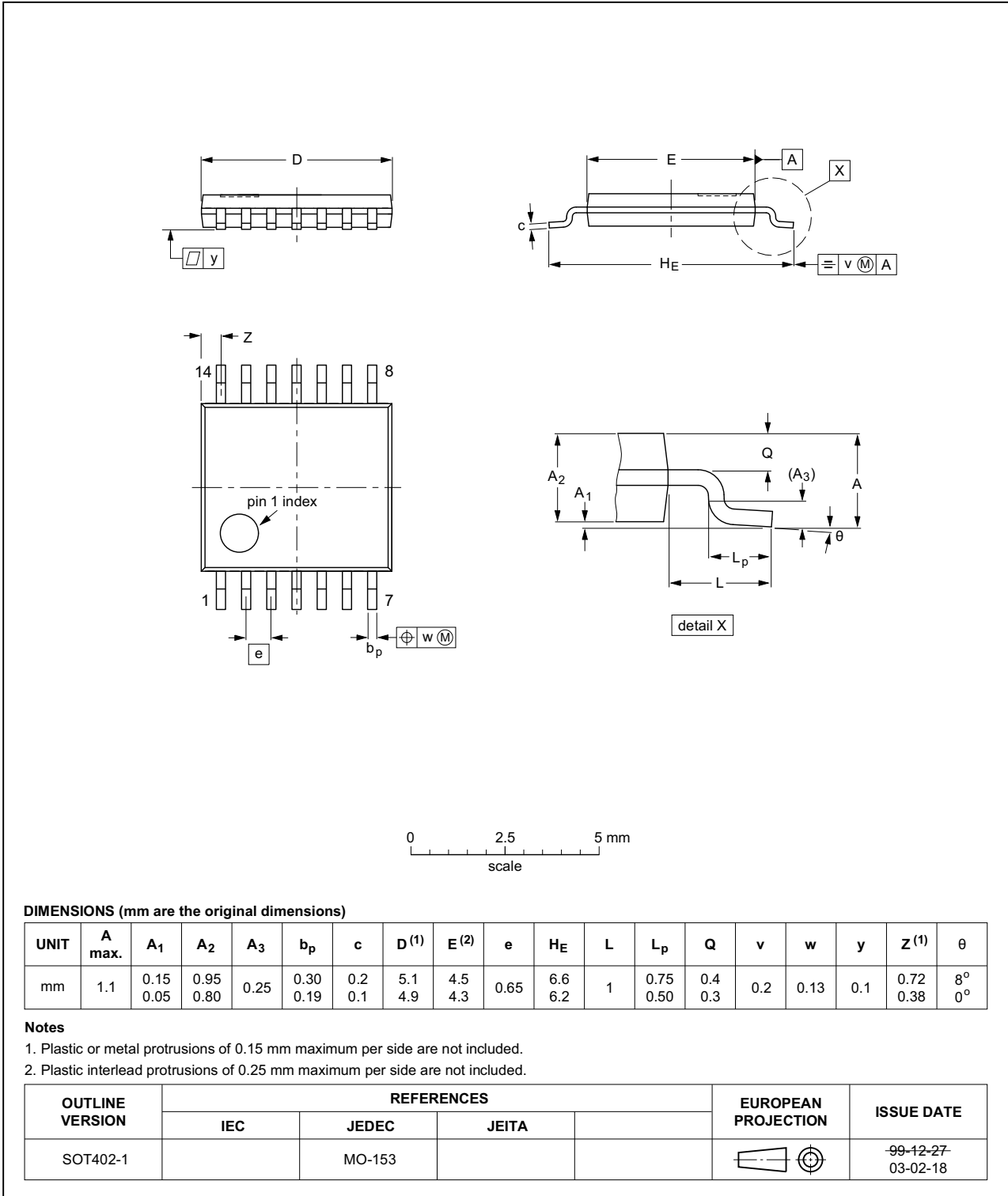


Fig 11. Package outline SOT402-1 (TSSOP14)

13. Abbreviations

Table 10. Abbreviations

| Acronym | Description |
|---------|--|
| CMOS | Complementary Metal Oxide Semiconductor |
| LSTTL | Low-power Schottky Transistor-Transistor Logic |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| MM | Machine Model |
| CDM | Charge-Device Model |
| TTL | Transistor-Transistor Logic |

14. Revision history

Table 11. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|---------------------|---|--------------------|---------------|---------------------|
| 74HC_HCT125 v.5 | 20150119 | Product data sheet | - | 74HC_HCT125 v.4 |
| Modifications: | <ul style="list-style-type: none"> Table 7: Power dissipation capacitance condition for 74HCT125 is corrected. | | | |
| 74HC_HCT125 v.4 | 20130110 | Product data sheet | - | 74HC_HCT125 v.3 |
| Modifications: | <ul style="list-style-type: none"> New general description. | | | |
| 74HC_HCT125 v.3 | 20120827 | Product data sheet | - | 74HC_HCT125_CNV v.2 |
| Modifications: | <ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. | | | |
| 74HC_HCT125_CNV v.2 | 19970827 | Product data sheet | - | - |

15. Legal information

15.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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